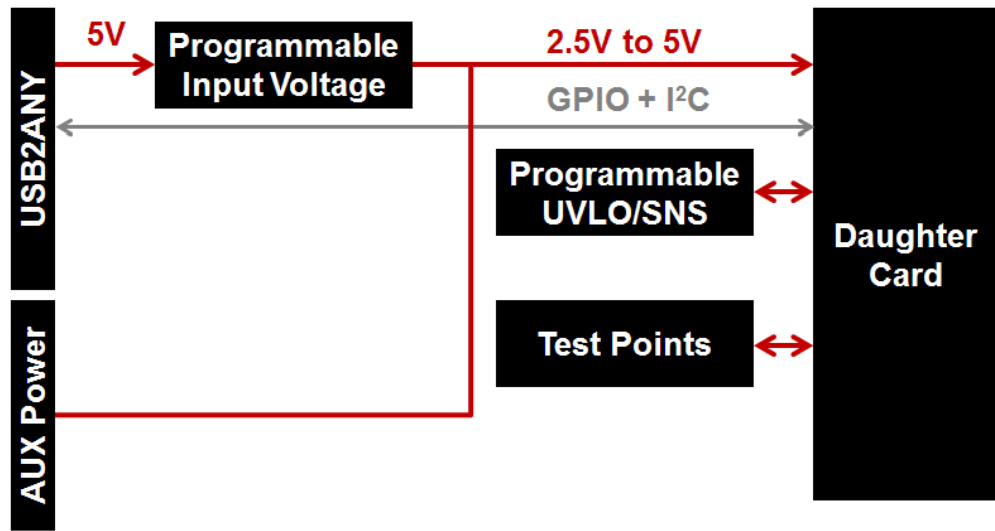


Revision History	
Revision	Notes
1.0	Initial release.

# TIDA-00399 SSD Power Delivery Interposer



TEXAS INSTRUMENTS



Layout Notes  
TID\_SSD\_Interposer\_Layout\_Notes.SchDoc



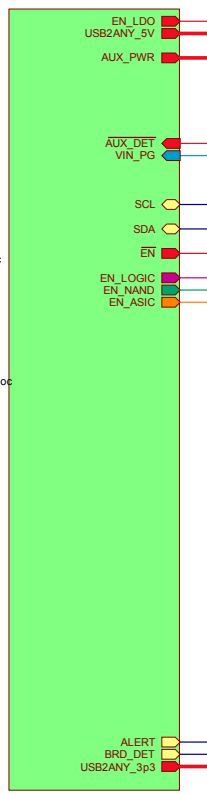
Hardware  
TID\_SSD\_Interposer\_Hardware.SchDoc



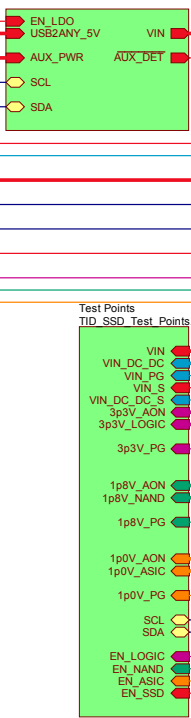
Coversheet  
TID\_SSD\_Interposer\_Coversheet.SchDoc



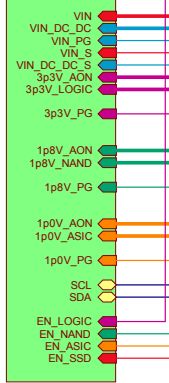
External Interfaces  
TID\_SSD\_External\_Interfaces.SchDoc



Power Selection  
TID\_SSD\_Power\_Selection.SchDoc



Test Points  
TID\_SSD\_Test\_Points.SchDoc



M2 Interface  
TID\_SSD\_Interposer\_M2\_Interface.SchDoc

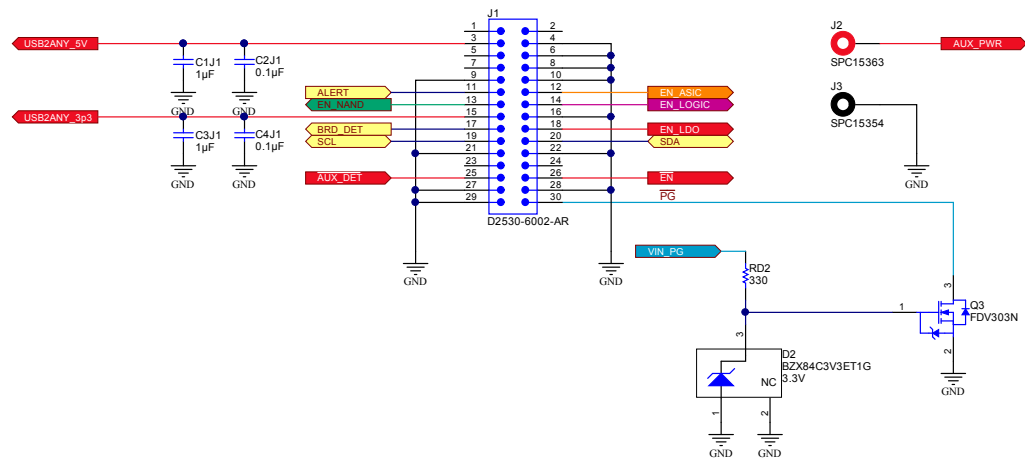


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TID #: 00399	Project Title: SSD Power Delivery - Interposer	
Number: TIDA-00399   Rev: E1	Sheet Title:	Sheet 2 of 8
Drawn By: Brian Lackey	Assembly Variant: 001	File: TID_SSD_Interposer.SchDoc
Engineer: Brian Lackey	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	Size: B



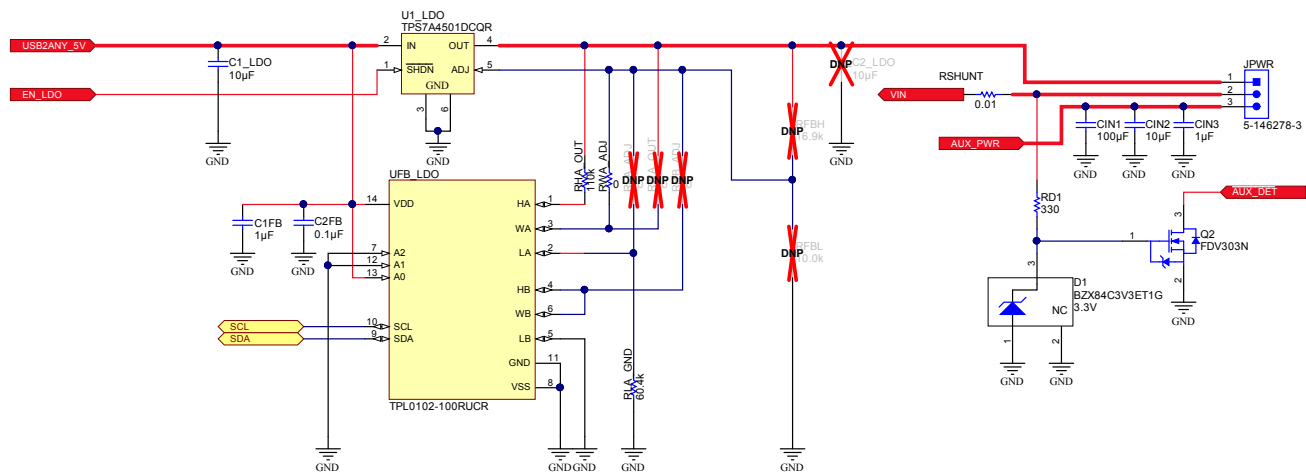
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Number: TIDA-00399   Rev: E1		Sheet Title:		Sheet 3 of 8	
Sponsor: Version control disabled		Assembly Variant: 001		Size: B	
Drawn By:		File: TID_SSD_External_Interfaces_SchDoc		http://www.ti.com	
Engineer: Brian Lackey		Contact: http://www.ti.com/support		© Texas Instruments 2014	

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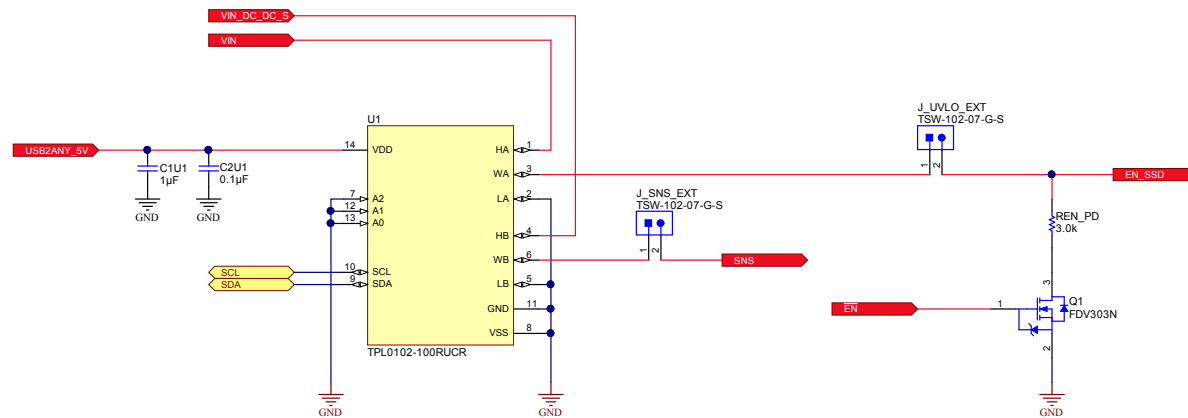


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Assembly Variant: 001	Sheet 4 of 8	
Drawn By: Brian Lackey	File: TID_SSD_Power_Selection_SchDoc	Size: B
Engineer: Brian Lackey	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



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Number: TIDA-00399   Rev: E1	Sheet Title:	Sheet: 5 of 8
Drawn By: Brian Lackey	Assembly Variant: 001	File: TID_SSD_UVLO and SNS_SchDoc
Engineer: Brian Lackey	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	Size: B



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1

2

3

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A

A

B

B

C

C

D

D

1

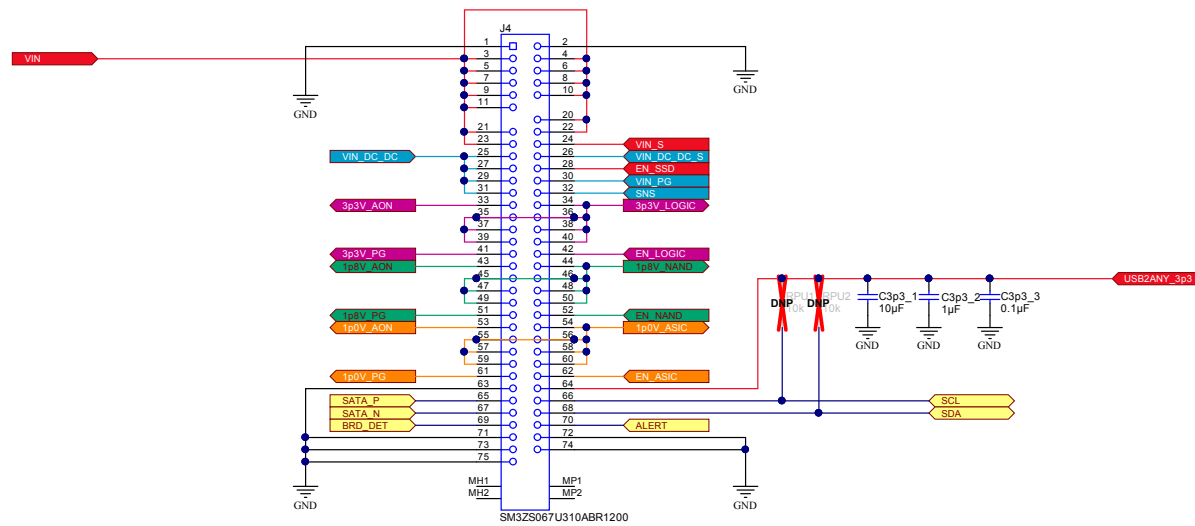
2

3

4

5

6





H1 NY PMS 440 0025 PH H2 NY PMS 440 0025 PH H3 NY PMS 440 0025 PH H4 NY PMS 440 0025 PH H9 NY PMS 440 0025 PH H11 NY PMS 440 0025 PH

H5 1902C H6 1902C H7 1902C H8 1902C H10 1902C H12 1902C

PCB Number: TIDA-00399  
PCB Rev: E1

PCB LOGO  
Texas Instruments

PCB LOGO  
Pb-Free Symbol

Label Table	
Variant	Label Text
001	Default

**ZZ2**  
**Assembly Note**  
These assemblies are ESD sensitive, ESD precautions shall be observed.

**ZZ3**  
**Assembly Note**  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

**ZZ4**  
**Assembly Note**  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

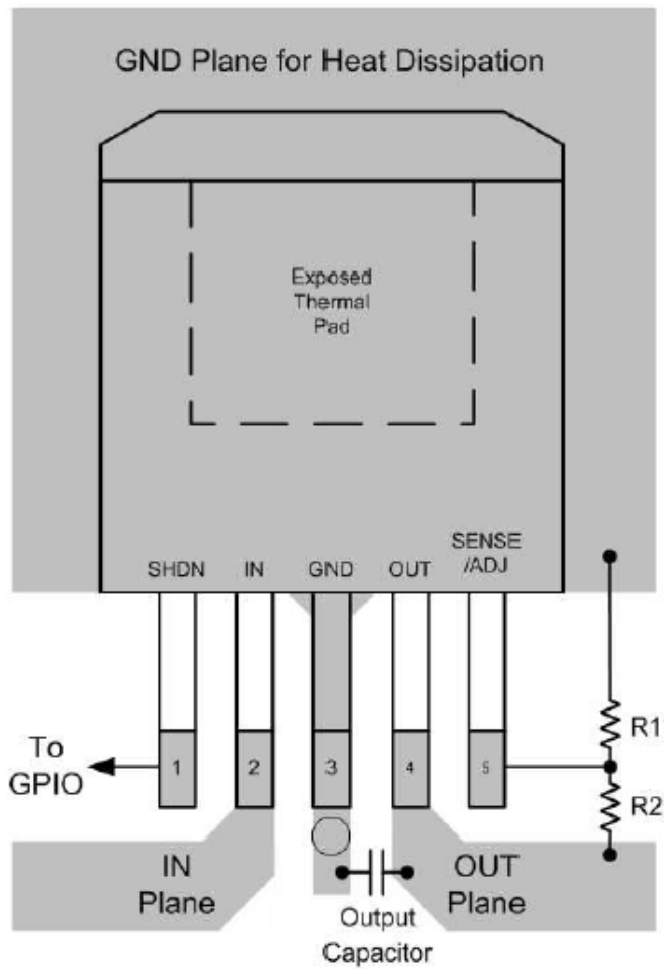
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Number: TIDA-00399   Rev: E1	Sheet Title:	Sheet: 8 of 8
Drawn By: Brian Lackey	File: TID_SSD_Interposer_Hardware_SchDoc	Size: B
Engineer: Brian Lackey	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



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○ Via to GND Plane

Figure 37. TO-263 Layout Example (KTT)

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Number: TIDA-00399   Rev: E1	Sheet Title:	Sheet: 9 of 9
Drawn By: Brian Lackey	Assembly Variant: 001	File: TID_SSD_Interposer_Layout_Notes_SchDoc   Size: B
Engineer: Brian Lackey	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	<a href="http://www.ti.com">http://www.ti.com</a>



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